

μPD5758T6J

Low Noise and High Gain Amplifier IC for Impedance Converter of Microphone

R09DS0017EJ0100

Rev.1.00

Apr 18, 2011

DESCRIPTION

The μPD5758T6J is a silicon MOS monolithic integrated circuit designed as high gain impedance converter for electret condenser microphone. This device exhibits low noise and high voltage gain characteristics.

The package is a 3-pin thin-type lead-less minimold, suitable for high-density surface mounting.

FEATURES

- Low noise : $N_V = -101$ dBV TYP. @ $V_{DD} = 1.5$ V, $C_{in} = 3$ pF, $R_L = 2.2$ kΩ
: $N_V = -102$ dBV TYP. @ $V_{DD} = 1.5$ V, $C_{in} = 5$ pF, $R_L = 2.2$ kΩ
- High gain : $G_V = +5.7$ dB TYP. @ $V_{DD} = 1.5$ V, $C_{in} = 3$ pF, $R_L = 2.2$ kΩ
: $G_V = +7.7$ dB TYP. @ $V_{DD} = 1.5$ V, $C_{in} = 5$ pF, $R_L = 2.2$ kΩ
- Low input capacitance : $C_{input} = 1.5$ pF TYP. @ $V_{DD} = 1.5$ V, $R_L = 2.2$ kΩ
- Low consumption current : $I_{DD} = 190$ μA TYP. @ $V_{DD} = 1.5$ V, $R_L = 2.2$ kΩ
- High-density surface mounting : 3-pin thin-type lead-less minimold ($1.2 \times 1.0 \times 0.33$ mm)
- Built-in the capacitor for RF noise immunity
- High ESD voltage

APPLICATIONS

- Microphone, Sensor etc.

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPD5758T6J-E4	μPD5758T6J-E4-A	3-pin thin-type lead-less minimold (Pb-Free)	6Y	<ul style="list-style-type: none"> Embossed tape 8 mm wide Pin 3 face the perforation side of the tape Qty 10 kpcs/reel

Remark To order evaluation samples, please contact your nearby sales office.

Part number for sample order: μPD5758T6J

CAUTION

Observe precautions when handling because these devices are sensitive to electrostatic discharge.

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Input Voltage (IN-GND)	V _{in}	−0.5 to +0.5	V
Input Current (IN-GND)	I _{in}	0.5	mA
Output Voltage (OUT-GND)	V _{out}	0 to +5	V
Output Current (OUT-GND)	I _{out}	0.5	mA
Channel Temperature	T _{ch}	130	°C
Operating Ambient Temperature	T _A	−40 to +85	°C
Storage Temperature	T _{stg}	−65 to +150	°C

RECOMMENDED OPERATING RANGE (T_A = +25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage ^{Note}	V _{DD}	1.0	1.5	5.0	V

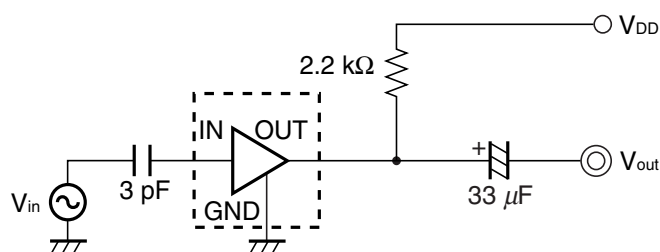
Note: R_L = 2.2 kΩ

ELECTRICAL CHARACTERISTICS (T_A = +25°C, R_L = 2.2 kΩ, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	I _{DD}	V _{DD} = 1.5V, V _{in} = 0 V	140	190	250	μA
Input Capacitance	C _{input}	V _{DD} = 1.5 V, f = 1 MHz	–	1.5	–	pF
Voltage Gain	G _V	V _{DD} = 1.5 V, V _{in} = 10 mVrms, C _{in} = 3 pF, f = 1 kHz, see TEST CIRCUIT	4.5	5.7	7.0	dB
Reduced Voltage Characteristics	ΔG _{VV}	V _{DD} = 1.5 → 1.0 V, V _{in} = 10 mVrms, C _{in} = 3 pF, f = 1 kHz, see TEST CIRCUIT	–	0.7	–	dB
Frequency Characteristics	ΔG _{Vf}	V _{DD} = 1.5 V, V _{in} = 10 mVrms, C _{in} = 3 pF, f = 1 kHz → 110 Hz, see TEST CIRCUIT	–	0	–	dB
Output Noise Voltage	N _V	V _{DD} = 1.5 V, V _{in} = 0 Vrms, C _{in} = 3 pF, A-Curve, see TEST CIRCUIT	–	−101	–	dBV
Total Harmonic Distortion	THD	V _{DD} = 1.5 V, V _{out} = 50 mVrms, C _{in} = 3 pF, f = 1 kHz, see TEST CIRCUIT	–	0.7	–	%

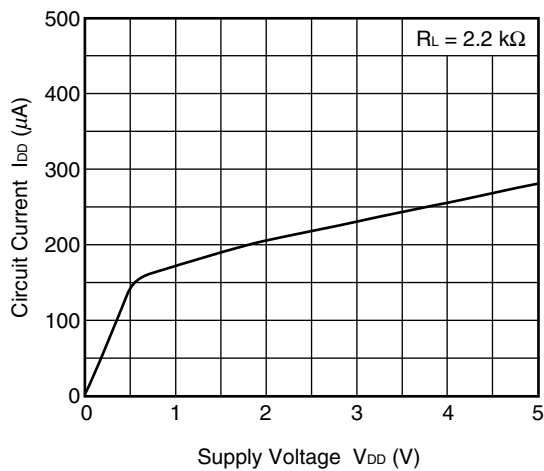
TEST CIRCUIT

Voltage Gain, Frequency Characteristics, Output Noise Voltage, Total Harmonic Distortion

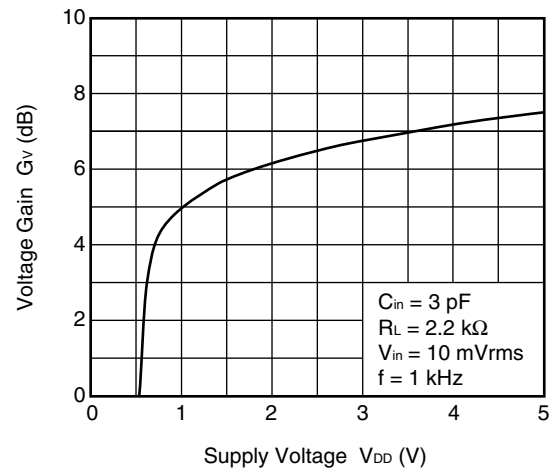


TYPICAL CHARACTERISTICS (T_A = +25°C, unless otherwise specified)

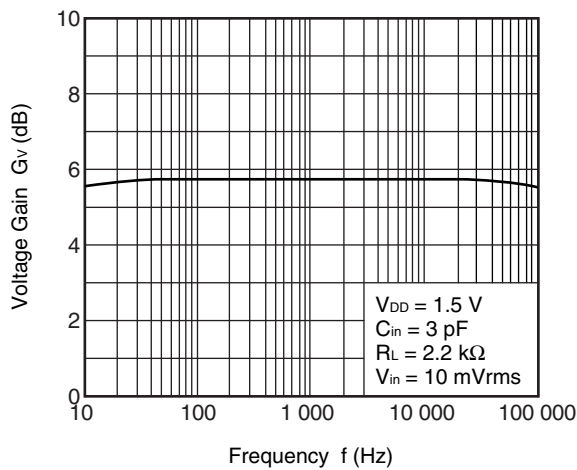
CIRCUIT CURRENT vs. SUPPLY VOLTAGE



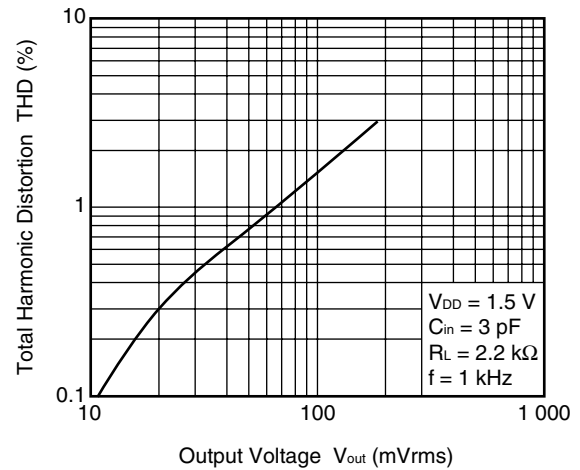
VOLTAGE GAIN vs. SUPPLY VOLTAGE



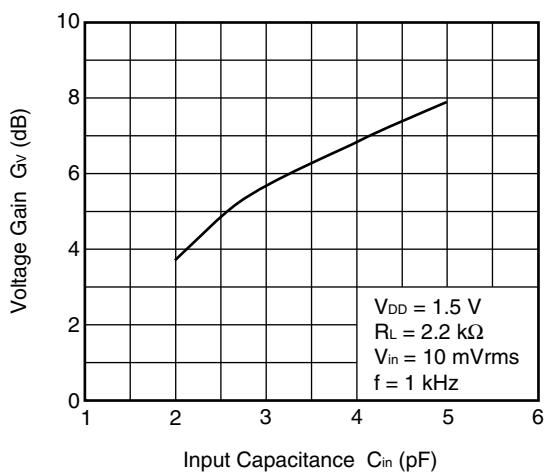
VOLTAGE GAIN vs. FREQUENCY



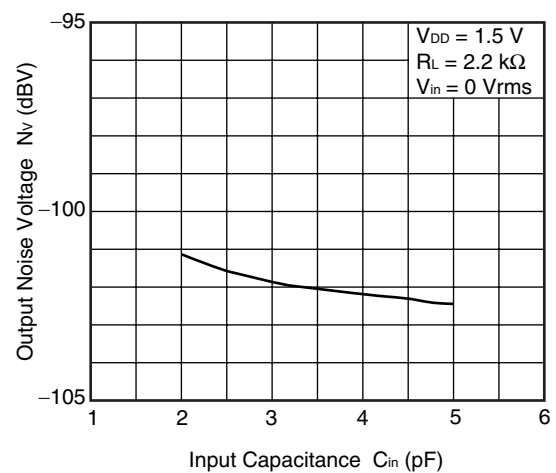
TOTAL HARMONIC DISTORTION vs. OUTPUT VOLTAGE



VOLTAGE GAIN vs. INPUT CAPACITANCE



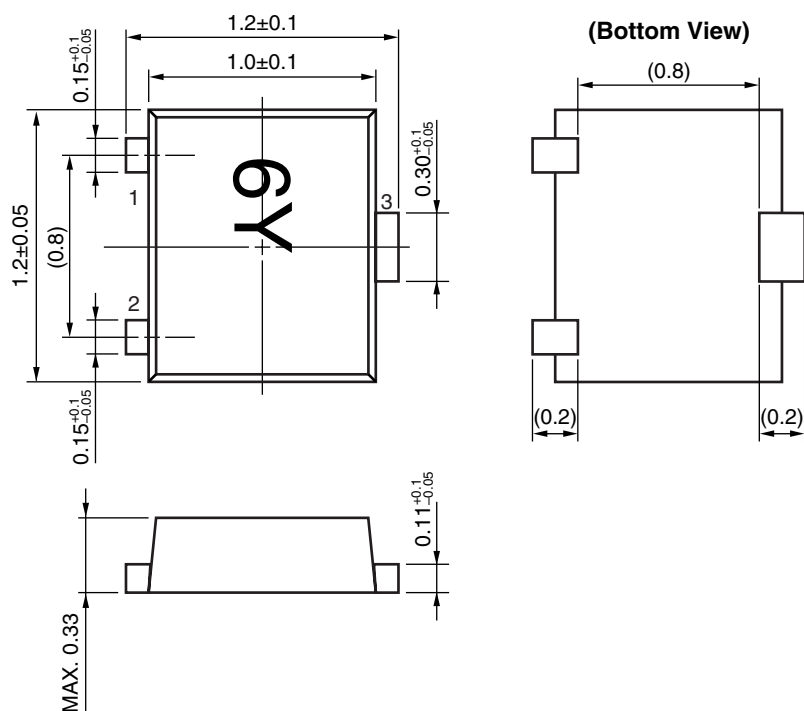
OUTPUT NOISE VOLTAGE vs. INPUT CAPACITANCE



Remark The graphs indicate nominal characteristics.

PACKAGE DIMENSIONS

3-PIN THIN-TYPE LEAD-LESS MINIMOLD (UNIT: mm)



PIN CONNECTIONS

1. OUT
2. IN
3. GND

Remark (): Reference value

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

CAUTION

Do not use different soldering methods together (except for partial heating).

Revision History	μPD5758T6J Data Sheet
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Rev.	Date	Description	
		Page	Summary
1.00	Apr 18, 2011	—	First edition issued

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Renesas Electronics America Inc.

2880 Scott Boulevard Santa Clara, CA 95050-2554, U.S.A.
Tel: +1-408-588-6000, Fax: +1-408-588-6130

Renesas Electronics Canada Limited

1101 Nicholson Road, Newmarket, Ontario L3Y 9C3, Canada
Tel: +1-905-898-5441, Fax: +1-905-898-3220

Renesas Electronics Europe Limited

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: +44-1628-585-100, Fax: +44-1628-585-900

Renesas Electronics Europe GmbH

Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-65030, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.

7th Floor, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100083, P.R.China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.

Unit 204, 205, AZIA Center, No.1233 Lujiazui Ring Rd., Pudong District, Shanghai 200120, China
Tel: +86-21-5877-1818, Fax: +86-21-6887-7858 / -7898

Renesas Electronics Hong Kong Limited

Unit 1601-1613, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2886-9318, Fax: +852 2886-9022/9044

Renesas Electronics Taiwan Co., Ltd.

7F, No. 363 Fu Shing North Road Taipei, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.

1 harbourFront Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: +65-6213-0200, Fax: +65-6278-8001

Renesas Electronics Malaysia Sdn.Bhd.

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics Korea Co., Ltd.

11F., Samik Laviel' or Bldg., 720-2 Yeoksam-Dong, Kangnam-Ku, Seoul 135-080, Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5141